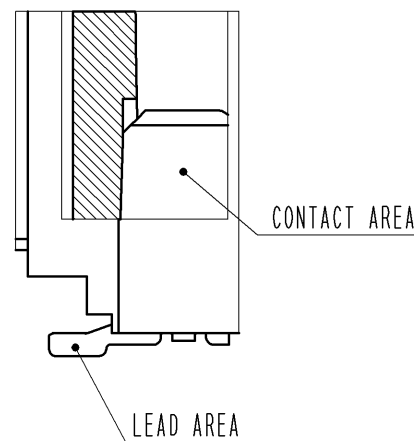
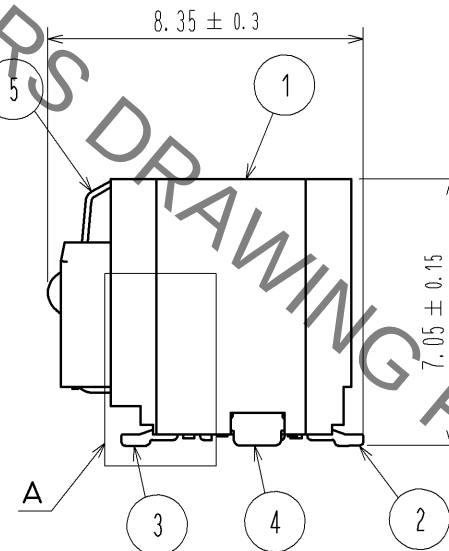
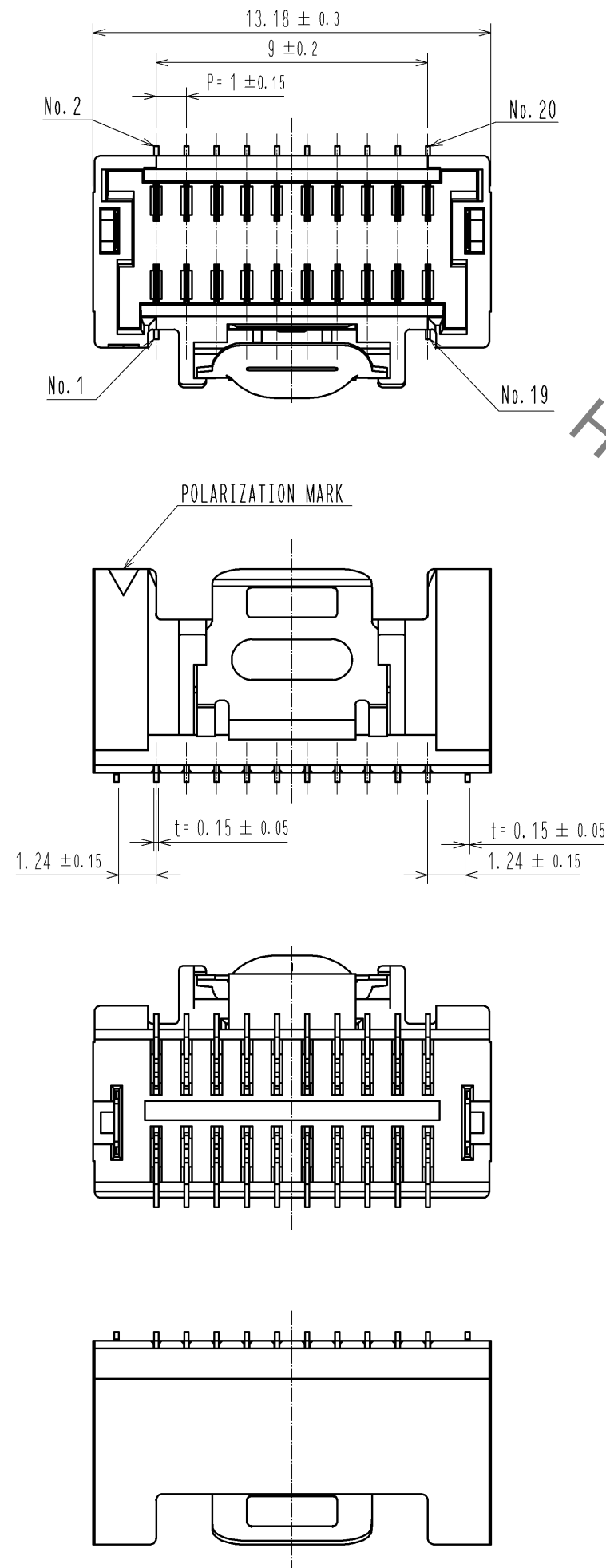
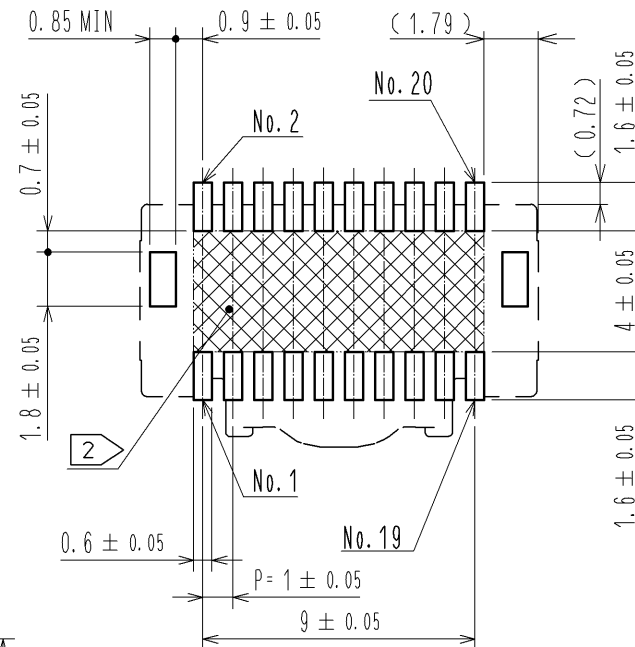


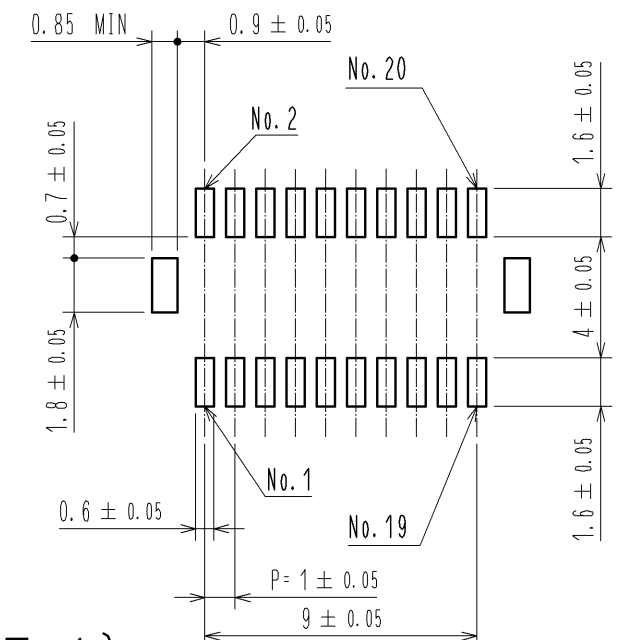


RECOMMENDED PCB LAYOUT (MOUNTING SURFACE SIDE) (FREE)

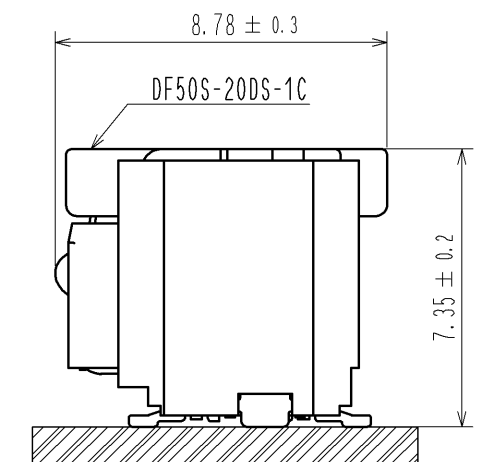
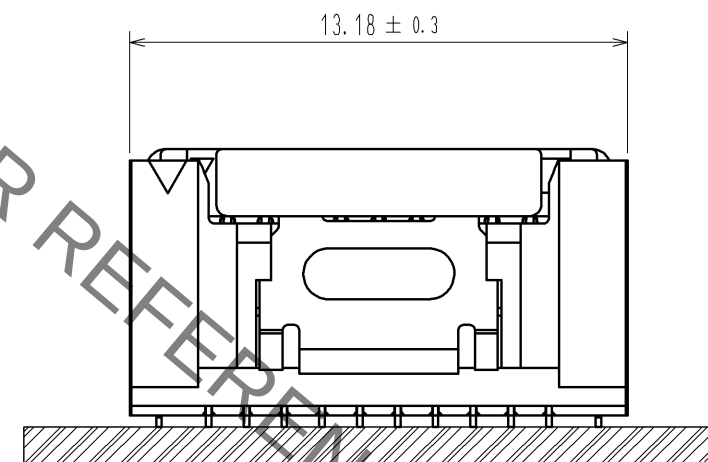


RECOMMENDED METAL MASK(FREE)

THICKNESS : 0.1mm



MATING FIGURE (5 : 1)



- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1 mm MAX.
2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

3	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN.	9	POLYAMIDE	VACUUM CAP
		LEAD AREA : Au PLATING 0.05μm MIN.	8	PS	REEL, BLACK
		UNDERPLATING : Ni PLATING 1μm MIN.	7	POLYESTER	CLEAR
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN.	6	PS	CLEAR
		LEAD AREA : Au PLATING 0.05μm MIN.	5	STAINLESS STEEL	-
		UNDERPLATING : Ni PLATING 1μm MIN.	4	BRASS	SURFACE : Sn PLATING 1μm MIN. UNDERPLATING : Ni PLATING 0.5μm MIN.
1	LCP	NATURAL, UL94V-0			
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
UNITS mm		SCALE FREE	COUNT		DESCRIPTION OF REVISIONS
					DESIGNED
					CHECKED
					DATE
HIROSE ELECTRIC CO., LTD.		APPROVED : KI. AKIYAMA	14.10.24	DRAWING NO. EDC3-339519-05	
		CHECKED : TS. FUKUSHIMA	14.10.24	PART NO. DF50-20DP-1V(62)	
		DESIGNED : HT. SATO	14.10.24	CODE NO. CL665-0019-3-62	
		DRAWN : MI. SAKIMURA	14.10.22		

